



# PCB Specification Datasheet

Date: 15-6-2009  
Document: KS0002 V0.4  
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Customer:

Contact:

Phone:

Email:

Date:

Document name:

Board type nr:

Board description:

Revision:

Article number:

Project:

Datacontainer:

### Board details

Number of layers  #

PCB Thickness  mm

PCB Size  x  mm

Panel  J/N

Max. Panel size  x  mm

### Mechanical

V-scoring  mm

Complex inner-rout  J/N

Minimum hole size  mm

Pressfit  J/N

Blind via's  J/N

Burried via's  J/N

### Materials

PCB base material

Finish

Finished Cu thickness  μ

Soldermask top  J/N

Soldermask bottom  J/N

Silkscreem top  J/N

Silkscreen bottom  J/N

Peel-off top  J/N

Peel-off bottom  J/N

Via plugging top  J/N

Via plugging bottom  J/N

### Lay-out details

Number of SMD sides  1 - 2

Minimum track  μ

Minimum gap  μ

Controlled Impedance  J/N

Selective Goldplating  J/N

### Markings

UL-Logo  J/N

Date code  J/N

### General

Documents attached  J/N

Stencil info retour  J/N

Electrical tested  J/N

### General remarks

# HEAD Electronics BV

www.head.nl



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### Lay-out details

Number of SMD sides  1 - 2  
Minimum track   $\mu\text{m}$   
Minimum gap   $\mu\text{m}$   
Controlled Impedance  J/N  
Selective Goldplating  J/N  
Copperbalancing allowed in lay-out  J/N  
Copperbalancing allowed in break-off tabs  J/N

### Markings

UL logo  J/N  
Date code  J/N  
Pb-free logo  J/N  
Vendor logo  J/N  
Electrical test  J/N

### General

Electrical test  J/N  
Stencil information retour  J/N  
Checkplots retour  J/N  
Stackup specified  J/N  
Documents attached  J/N

Email:   
Email:

### Warranty remarks

### Packaging remarks

### General remarks